



NGF-40S1x-x-S268

鍍層厚度:

Blank : 1u"

2 : 15u"

3 : 30u"

M	-6.125	14.0	2.0	14.0	1.5	1.125	1.375
L	-5.125	13.0	3.0	13.0	2.5	1.125	1.375
K	-4.125	12.0	4.0	12.0	3.5	1.125	1.375
J	-3.125	11.0	5.0	11.0	4.5	1.125	1.375
H	-2.125	10.0	6.0	10.0	5.5	1.125	1.375
G	-1.125	9.0	7.0	9.0	6.5	1.125	1.375
F	1.625	6.5	9.5	6.0	9.5	1.375	1.125
E	2.625	5.5	10.5	5.0	10.5	1.375	1.125
D	3.625	4.5	11.5	4.0	11.5	1.375	1.125
C	4.625	3.5	12.5	3.0	12.5	1.375	1.125
B	5.625	2.5	13.5	2.0	13.5	1.375	1.125
A	6.625	1.5	14.5	1.0	14.5	1.375	1.125
KEY NAME	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G

MATERIAL:

1.1 Housing: LCP,Black

1.2 Contact: Phosphor Bronze

1.3 Solder Peg: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Gold Plated on Solder Balls ;

Nickel under plated overall

2.2 Solder Peg: Tin Plated on Solder Balls

Nickel under plated overall

CONTACT

建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 07/22/22
DATE: 07/22/22
DATE: 07/22/22

MAT'L
FINISH
SCALE

1 : 1

TITLE
MODLE
DWG NO.

CONNECTOR
NGFF 0.5PITCH 67P H:4.0
NGF-40S1x-x-S268

SIZE
A4
VER
R

